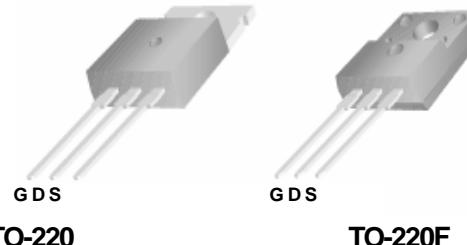
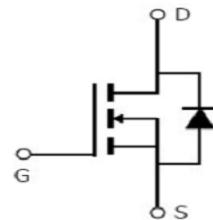


Features

- $R_{DS(on)}$ (Typical 2.6Ω)@ $V_{GS}=10V$
- Improved dv/dt Capability, High Ruggedness
- 100% Avalanche Tested
- Maximum Junction Temperature Range (150°C)

**Absolute Maximum Ratings**

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Symbol	Parameter	Rating		Unit
		TO-220	TO-22F	
Common Ratings ($T_J=25^{\circ}C$ Unless Otherwise Noted)				
V_{GS}	Gate-Source Voltage	±30		V
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	600		V
T_J	Maximum Junction Temperature	50 to + 150		°C
T_{STG}	Storage Temperature Range	50 to + 150		°C
I_s	Diode Continuous Forward Current	4		A
Mounted on Large Heat Sink ($T_J=25^{\circ}C$ Unless Otherwise Noted)				
I_{DM}	Pulse Drain Current Tested (Silicon Limit) (Note1)	16		A
I_D	Continuous Drain current@ $V_{GS}=10V$	$T_c=25^{\circ}C$	4	A
P_D	Maximum Power Dissipation	109	39	W
E_{AS}	Sing Pulsed Avalanche Energy ^(Note2)	200	200	mJ
$R_{\theta JC}$	Thermal Resistance Junction-to-Case	1.15	3.2	°C/W
$R_{\theta JA}$	Thermal Resistance Junction-to-Ambient	65	65	°C/W

Note :

1. Repetitive Rating:Pulse width limited by maximum junction temperature.

2. IL=25mH,IAS=4 A,VDD=50V,RG=25Ω,Tj=25 °C

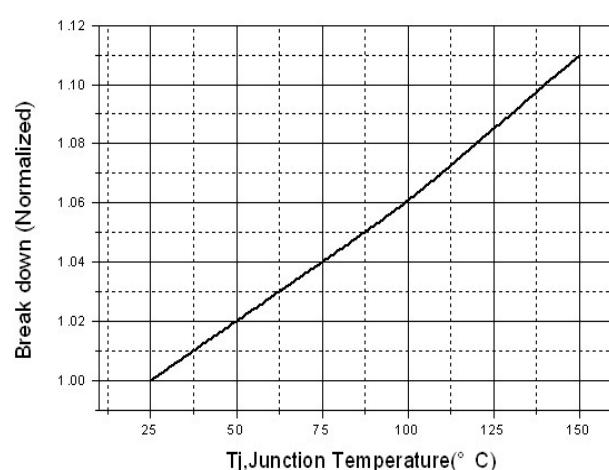
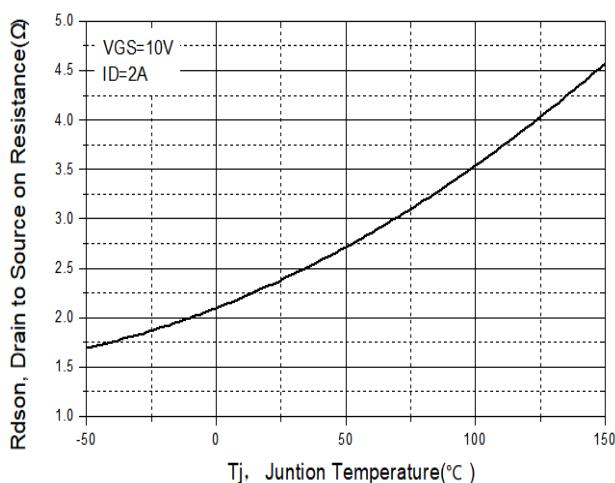
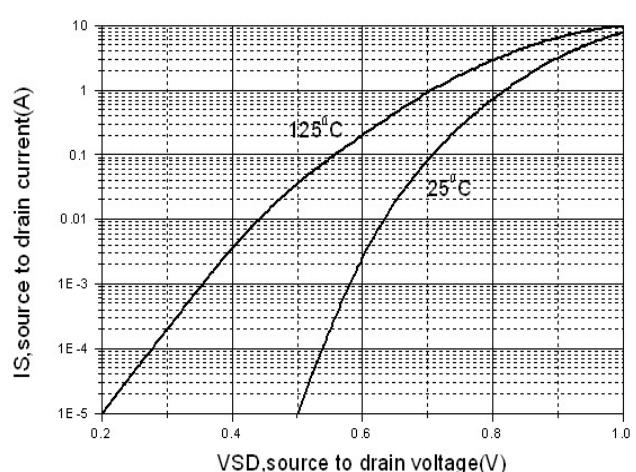
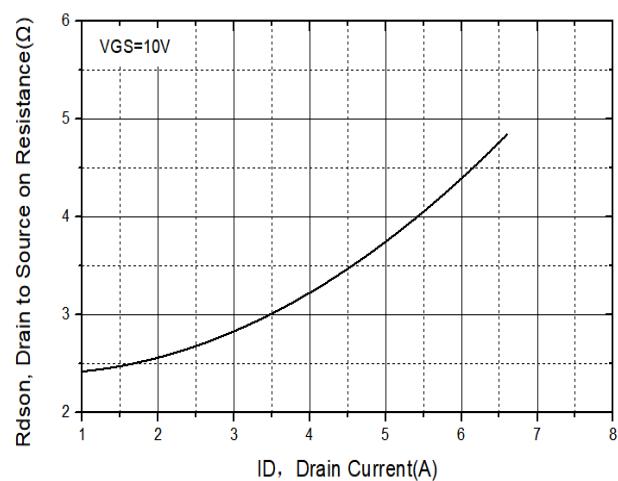
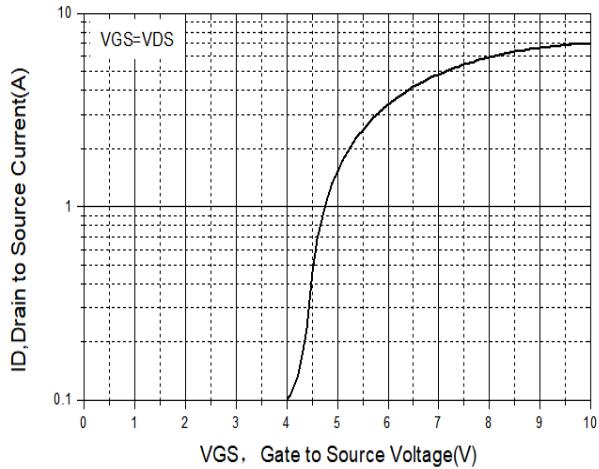
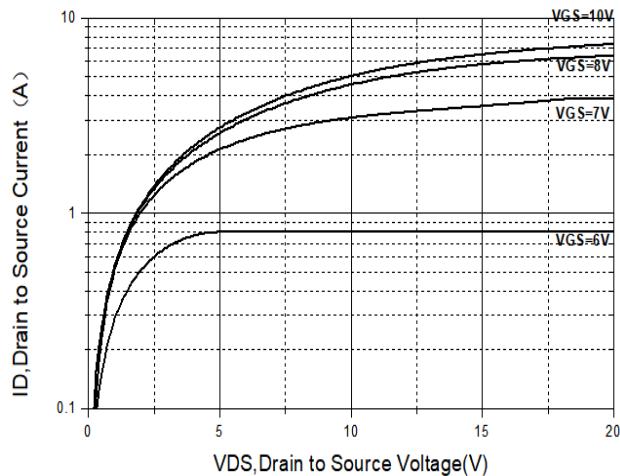
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ $ID=250\mu\text{A}$	600	--	--	V
I_{DSS}	Zero Gate Voltage Drain current($T_c=25^\circ\text{C}$)	$V_{DS}=600\text{V}, V_{GS}=0\text{V}$	--	--	1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 30\text{V}, V_{DS}=0\text{V}$	--		± 100	nA
$V_{\text{GS(TH)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, ID=250\mu\text{A}$	2	3	4	V
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance note A	$V_{GS}=10\text{V}, ID=2\text{A}$	--	2.6	3.0	Ω
Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated) ^{note B}						
C_{iss}	Input Capacitance	$V_{DS}=25\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	--	550	--	pF
C_{oss}	Output Capacitance		--	46	--	pF
C_{rss}	Reverse Transfer Capacitance		--	2.3	--	pF
Q_g	Total Gate Charge	$V_{DS}=480\text{V}, ID=4\text{A}$ $V_{GS}=10\text{V}$	--	10.2	--	nC
Q_{gs}	Gate-Source Charge		--	2.3	--	nC
Q_{gd}	Gate-Drain Charge		--	2.1	--	nC
Switching Characteristics ^{note B}						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{DS}=300\text{V}$ $ID=4\text{A}, RG=25\Omega$ $V_{GS}=10\text{V}$	--	15.5	--	nS
t_r	Turn-on Rise Time		--	13	--	nS
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	40	--	nS
t_f	Turn-Off Fall Time		--	16	--	nS
Source- Drain Diode Characteristics@ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
V_{SD}	Forward on voltage	$IS=4\text{ A}, V_{GS}=0\text{V}$	--	0.8	1.4	V

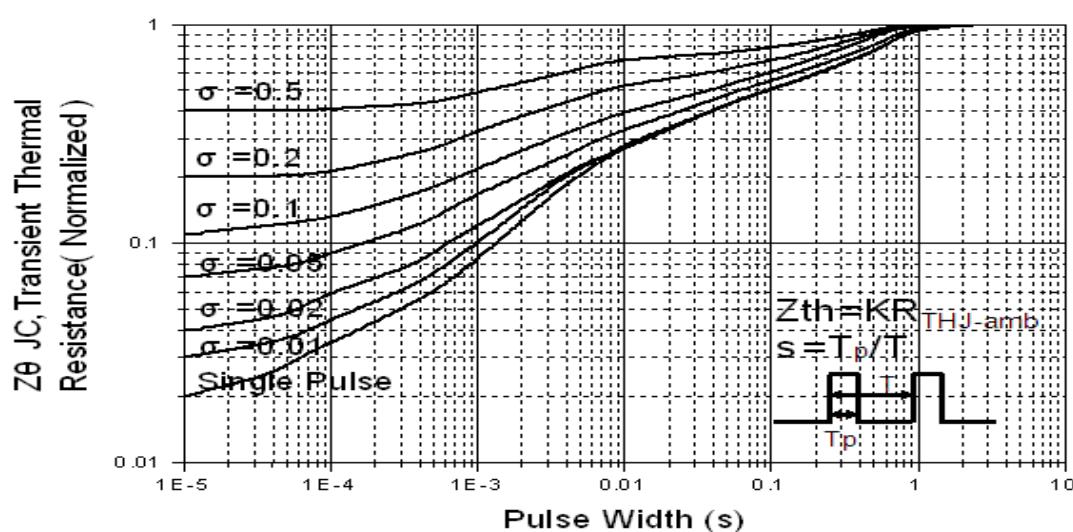
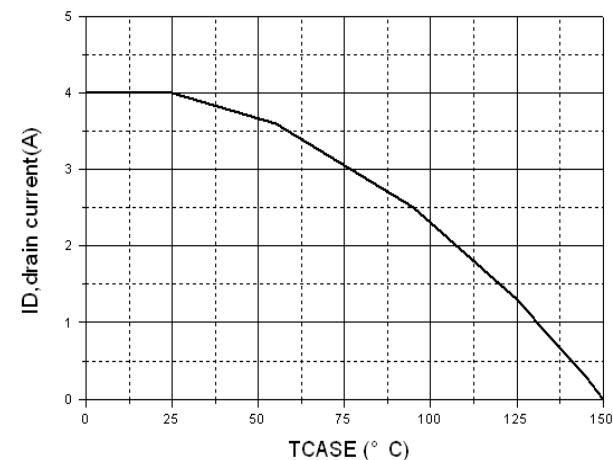
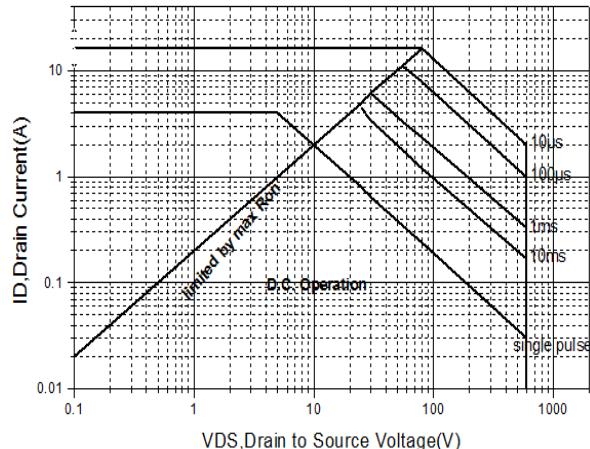
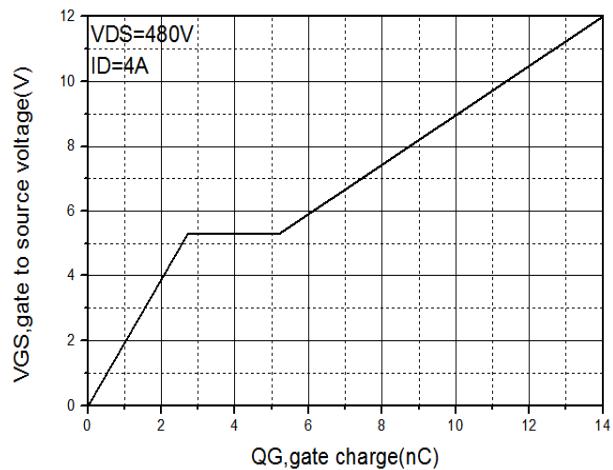
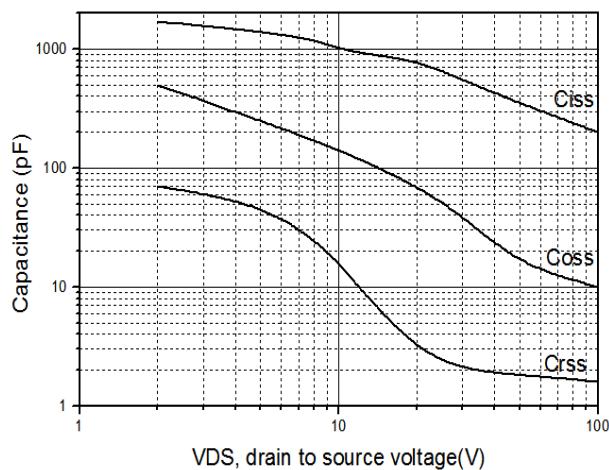
Note:

A: Pulse Test: pulse width $\leq 300\text{ us}$, duty cycle $\leq 2\%$

B: Guranteed by design, not subject to production testing.

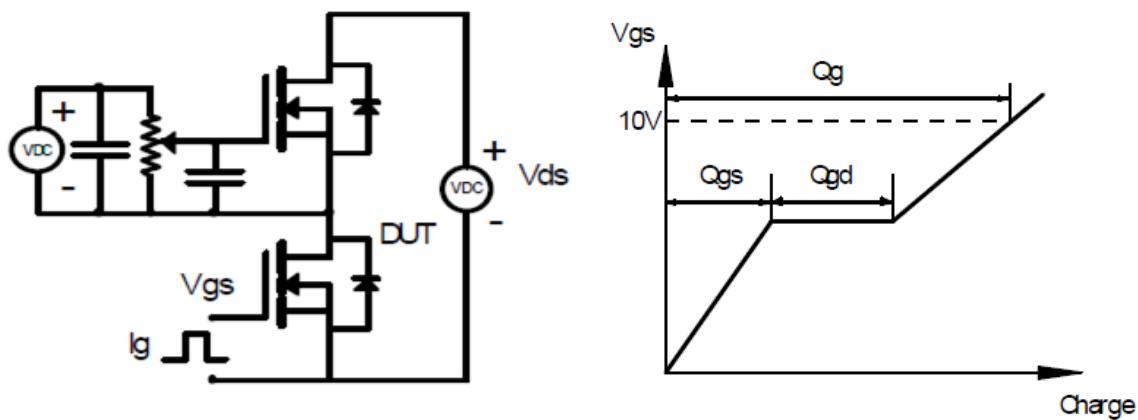
Typical characteristic curve:



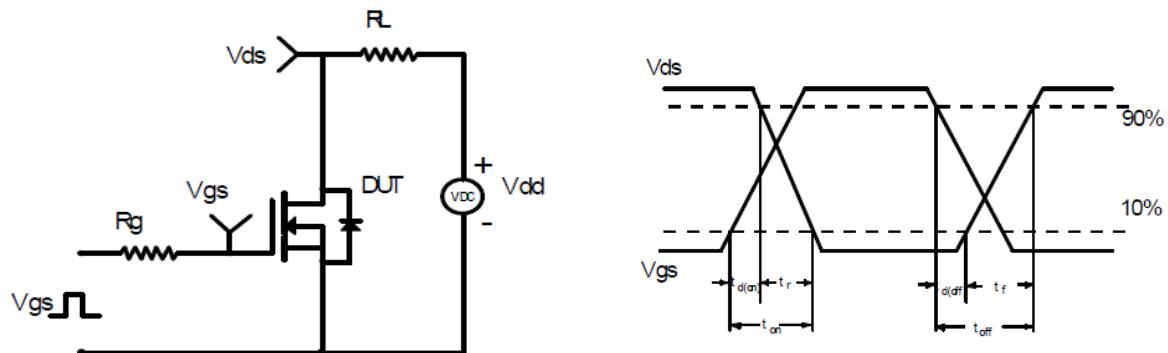


Test Circuit and Waveform

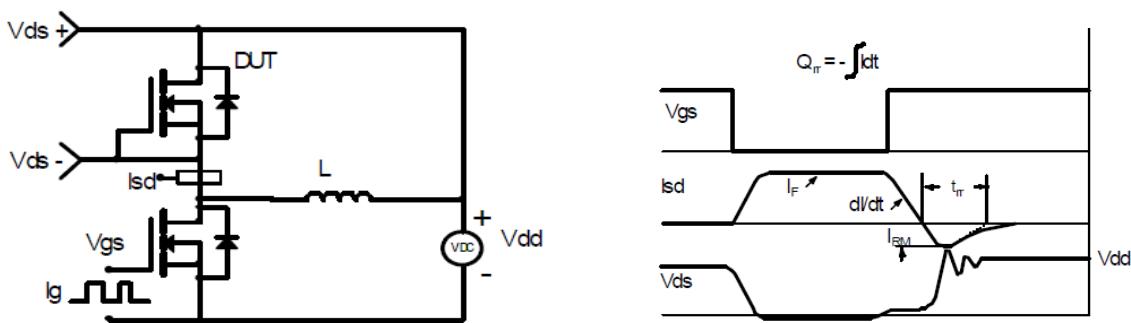
Gate Charge Test Circuit and Waveform



Switching time test circuit and waveform



Reverse Recovery Test Circuit and Waveform



Avalanche Test Circuit and Waveform

